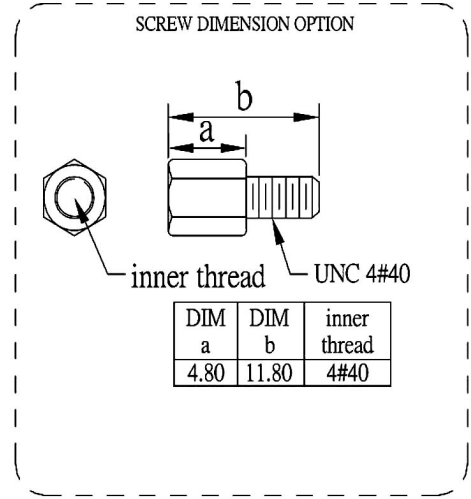


MATERIAL
 HOUSING : HIGH TEMPERATURE HOUSING
 LCP (UL94V-0)WITHSTANDS IR AND
 VPR SOLDERING METHODS.
 CONTACTS : BRONZE.
 PLATING : SELECTIVE GOLD PLATED.

SPECIFICATION
 CURRENT RATING : 1AMP.
 INSULATOR RESISTANCE 5000MΩ MIN.AT DC 500V.
 CONTACT RESISTANCE : 20MΩ MAX.AT DC 100mA.
 OPERATING TEMPERATURE : -65°C~+125°C.
 MAX PROCESSING TEMPERATURE: 260±10°C FOR 3~5 SECONDS.



RoHS Compliant		HSM 玄茂科技股份有限公司 HSUAN MAO TECHNOLOGY CO., LTD.	
APPD. 核准	SCALE 比例 参考	TOLERANCE 0±0.30 .00±0.20 .000±0.050 .0000±0.0000 ANG.±3°	PART NAME 品名 D-SUB PCB R/A FOR NOTEBOOK SMT TYPE 9P MALE THREAD INSERT 4-40UNC WITH BOARDLOCK FIX SCREWS 4.8*11.8mm SELECTIVE GOLD PLATING BLACK COLOR MATERIAL: LCP (POST SPACING=15.9mm) ROHS
DWG. 製圖	UNIT 單位	SIZE 紙張尺寸	PART NO.
DATE 制表日	PAGE 張數	REV. 版次	料號
2018/05/16	1 OF 1	A	C0527-09MBCXSBN

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